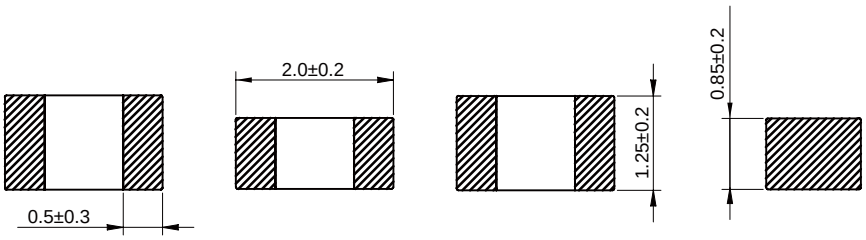
Chip Ferrite Bead SMD Type
Size 0805

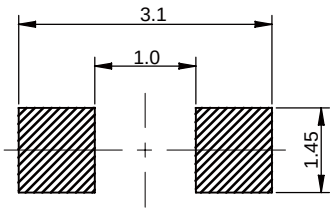


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Dimensions: [mm]



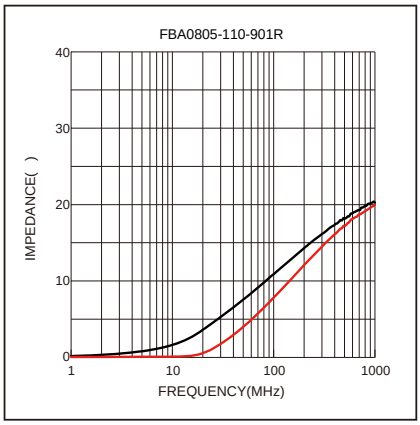
Land Pattern: [mm]

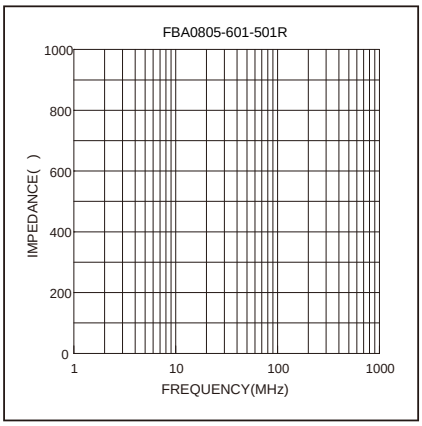


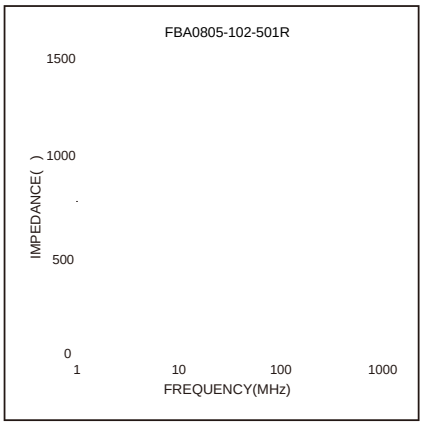
Electrical Properties:

	Impedance @ 100MHz (Ω)	DC Resistance Max. (Ω)	Temperature Rise Current Max. (mA)
	%		
& ìôìñrííìrõìíZ	íí		
& ìôìñríóìròìíZ	íó		
& ìôìñrîòìròìíZ	îò		
& ìôìñrïììròìíZ	ïì		
& ìôìñrðììròìíZ	ðì		
& ìôìñròììrõìíZ	òì		
& ìôìñríîírôìíZ	íîì		
& ìôìñríñírôìíZ	íñì		
& ìôìñrîîíróñíZ	îîì		
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& ìôìñrðóíróìíZ	ðóì		
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& ìôìñríìîrðìíZ	íìì		
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Typical Electrical Characteristics:




FBA0805-601-501R
IMPEDANCE( )
1000
800
600
400
200
0
1
10
100
1000
FREQUENCY(MHz)


FBA0805-102-501R
IMPEDANCE( )
1500
1000
500
0
1
10
100
1000
FREQUENCY(MHz)

Soldering Reflow:

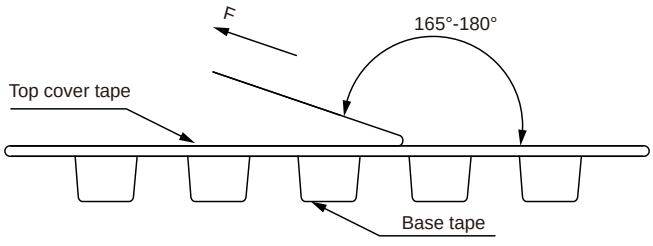
Packaging Information:

Tape Dimension:



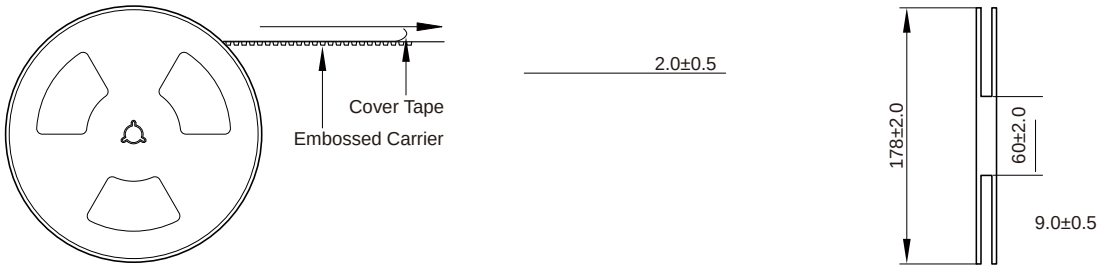
Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
0805	1.30±0.05	2.10±0.05	1.5±0.1	4.0±0.1	4.0±0.1	8.0±0.3	0.95±0.05	1.75±0.1	0.95±0.05

Peel force of top cover tape:



The peel force of top cover tape shall be between 0.14 to 0.58 N

Reel Dimension：[mm]



Cautions and Warnings:

Storage Conditions：

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max).If the storage period elapses, the soldering of the terminal electrodes may deteriorate.The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components.The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications.If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does.As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.